

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10	("5940716" "5981356" "6080637" "6093621 " "6583060").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:06
L2	6447	438/184,285,289,291,301-308.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:17
L3	5091	257/19,192,288,344,408,900.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:18
L4	11087	2 or 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:18
L5	180	4 and ((first near (recess\$2 groove\$2 open\$3)) WITH (second near (recess\$2 groove\$2 open\$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:21
L6	2	5 and (recess\$2 groove\$2 open\$3) WITH (stress near2 material\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:22
L7	2	4 and (recess\$2 groove\$2 open\$3) WITH (stress near2 material\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:22
L8	1020	(recess\$2 groove\$2 open\$3) WITH (stress near2 material\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:50
L9	181766	(recess\$2 groove\$2 open\$3) WITH (epi\$6 epitaxial\$2 silicon Si)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:30

L10	54	9 and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:26
L11	127716	(trench\$2 hole\$1 via\$1) WITH (epi\$6 epitaxial\$2 silicon Si)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:30
L12	735	(trench\$2 hole\$1 via\$1) WITH (stress near2 material\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:31
L13	134	12 and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2006/01/07 13:31
L14	5	("4835115" "5254873" "5913125" "6037237" "6090714").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/07 13:46
L15	1	(method process\$3 form\$3) AND substrate AND semiconductor AND gate AND fill\$3 AND align\$4 AND mandrel AND dummy AND spacer\$1 AND (void\$1 open\$3 hole\$1 recess\$2 groove\$1 via\$1) AND (first near (recess\$2 groove\$2 open\$3)) AND (second near (recess\$2 groove\$2 open\$3)) AND (stress near2 material\$1).CLM.	US-PGPUB; USPAT	OR	ON	2006/01/07 13:53